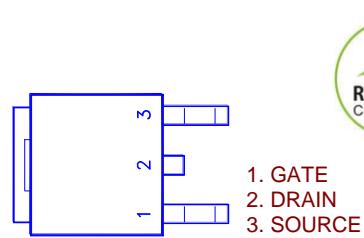
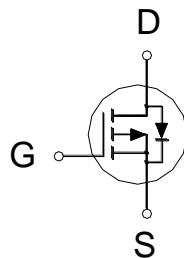


NIKO-SEM
**P-Channel Enhancement Mode
Field Effect Transistor**
PD533BA
TO-252
Halogen-Free & Lead-Free
PRODUCT SUMMARY

$V_{(BR)DSS}$	$R_{DS(ON)}$	I_D
-40V	14mΩ	-51A

**ABSOLUTE MAXIMUM RATINGS ($T_A = 25^\circ\text{C}$ Unless Otherwise Noted)**

PARAMETERS/TEST CONDITIONS		SYMBOL	LIMITS		UNITS
Drain-Source Voltage		V_{DS}	-40		V
Gate-Source Voltage		V_{GS}	±25		V
Continuous Drain Current ²	$T_C = 25^\circ\text{C}$	I_D	-51		A
	$T_C = 100^\circ\text{C}$		-40		
Pulsed Drain Current ¹		I_{DM}	-150		
Avalanche Current		I_{AS}	-38		
Avalanche Energy	$L = 0.1\text{mH}$	E_{AS}	72.2		mJ
Power Dissipation	$T_C = 25^\circ\text{C}$	P_D	65		W
	$T_C = 100^\circ\text{C}$		42		
Junction & Storage Temperature Range		T_J, T_{stg}	-55 to 150		°C

THERMAL RESISTANCE RATINGS

THERMAL RESISTANCE	SYMBOL	TYPICAL	MAXIMUM	UNITS
Junction-to-Case	$R_{\theta JC}$		1.9	
Junction-to-Ambient	$R_{\theta JA}$		62.5	°C / W

¹Pulse width limited by maximum junction temperature.²Package limitation current is -40A.**ELECTRICAL CHARACTERISTICS ($T_J = 25^\circ\text{C}$, Unless Otherwise Noted)**

PARAMETER	SYMBOL	TEST CONDITIONS	LIMITS			UNIT
			MIN	TYP	MAX	
STATIC						
Drain-Source Breakdown Voltage	$V_{(BR)DSS}$	$V_{GS} = 0\text{V}, I_D = -250\mu\text{A}$	-40			V
Gate Threshold Voltage	$V_{GS(\text{th})}$	$V_{DS} = V_{GS}, I_D = -250\mu\text{A}$	-1	-1.8	-3	
Gate-Body Leakage	I_{GSS}	$V_{DS} = 0\text{V}, V_{GS} = \pm 25\text{V}$			±100	nA
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS} = -32\text{V}, V_{GS} = 0\text{V}$			-1	
		$V_{DS} = -30\text{V}, V_{GS} = 0\text{V}, T_J = 125^\circ\text{C}$			-10	μA

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Drain-Source On-State Resistance ¹	R _{DS(ON)}	V _{GS} = -4.5V, I _D = -15A		14	20	mΩ
		V _{GS} = -10V, I _D = -20A		10	14	
Forward Transconductance ¹	g _{fs}	V _{DS} = -5V, I _D = -20A		50		S
DYNAMIC						
Input Capacitance	C _{iss}	V _{GS} = 0V, V _{DS} = -20V, f = 1MHz		2670		pF
Output Capacitance	C _{oss}			313		
Reverse Transfer Capacitance	C _{rss}			222		
Gate Resistance	R _g	V _{GS} = 0V, V _{DS} = 0V, f = 1MHz		4.5		Ω
Total Gate Charge ²	Q _g (V _{GS} =-10V)	V _{DS} = -20V, I _D = -20A		58		nC
	Q _g (V _{GS} =-4.5V)			29		
Gate-Source Charge ²	Q _{gs}			9		
Gate-Drain Charge ²	Q _{gd}			14		
Turn-On Delay Time ²	t _{d(on)}			29		nS
Rise Time ²	t _r			20		
Turn-Off Delay Time ²	t _{d(off)}	I _D ≈ -20A, V _{GS} = -10V, R _{GEN} = 6Ω		90		
Fall Time ²	t _f		41			
SOURCE-DRAIN DIODE RATINGS AND CHARACTERISTICS (T_J = 25 °C)						
Continuous Current ³	I _S				-50	A
Forward Voltage ¹	V _{SD}	I _F = -20A, V _{GS} = 0V			-1.3	V
Reverse Recovery Time	t _{rr}	I _F = -20A, dI _F /dt = 100A / μS		17		nS
Reverse Recovery Charge	Q _{rr}			6		nC

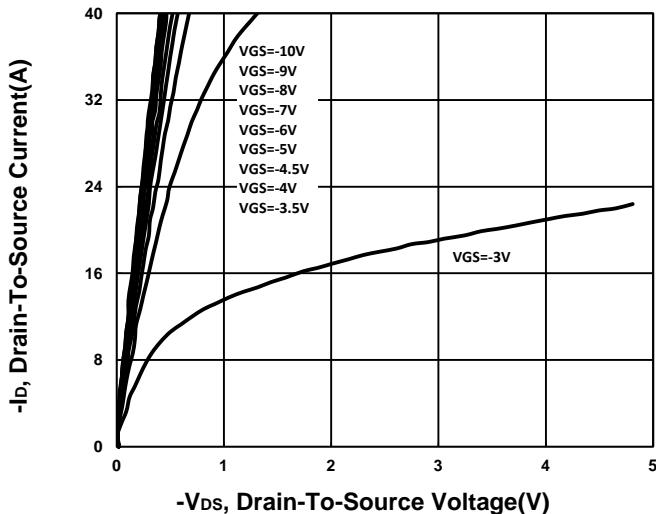
¹Pulse test : Pulse Width ≤ 300 μsec, Duty Cycle ≤ 2%.²Independent of operating temperature.³Package limitation current is -40A.

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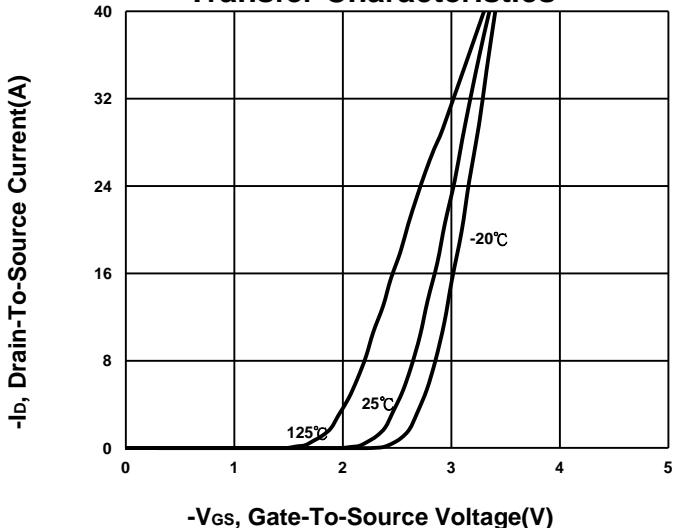
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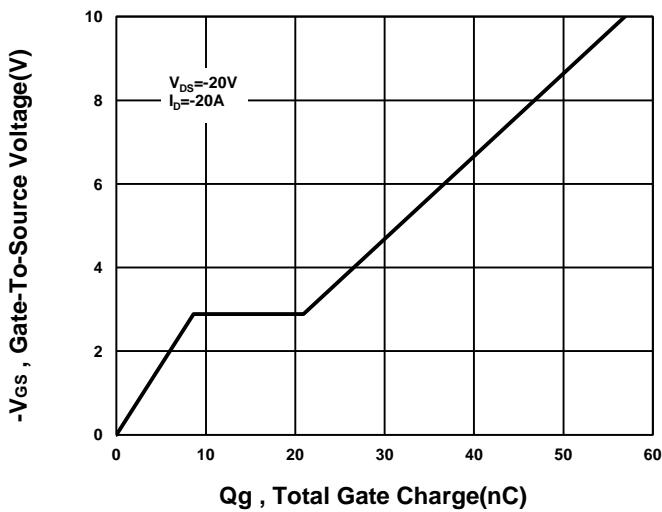
Output Characteristics



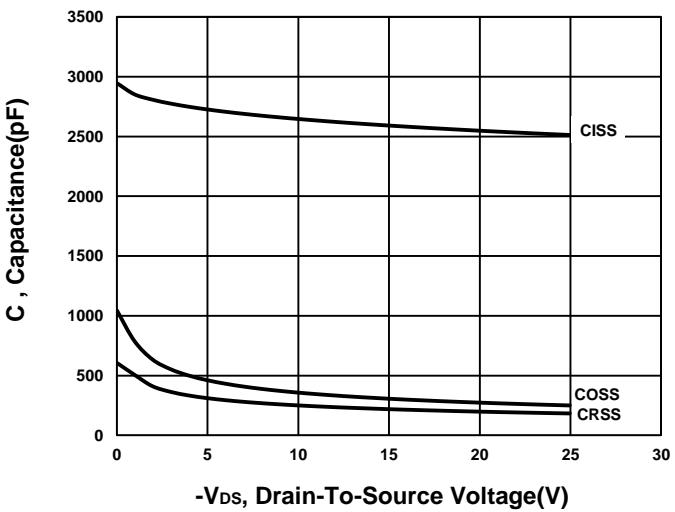
Transfer Characteristics



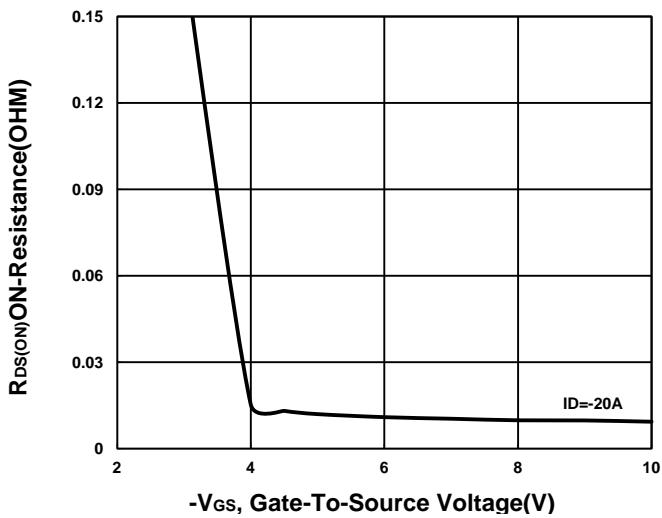
Gate charge Characteristics



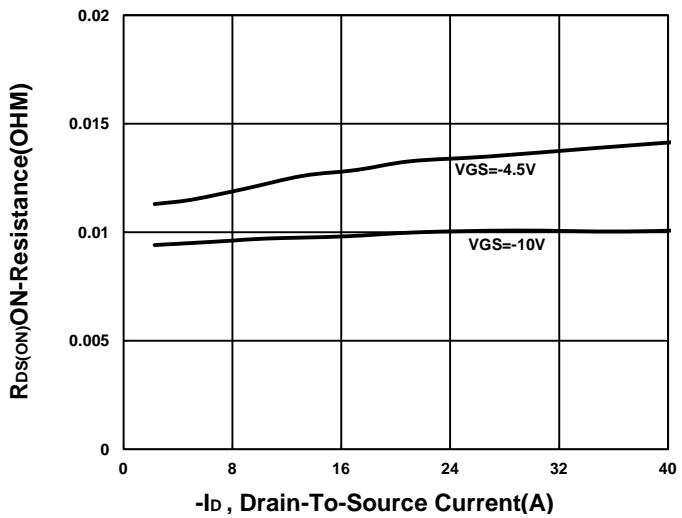
Capacitance Characteristic



On-Resistance VS Gate-To-Source



On-Resistance VS Drain Current



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